

IKO enertherm Upstand Board

For use on upstands and parapet walls

Product description

IKO enertherm Upstand Board is a laminate of IKO enertherm high performance rigid extruded polystyrene (XPS) with a tough, weather resistant facing board.

Applications

IKO enertherm Upstand Board is used for the thermal insulation and protection at upstand, parapet walls and protrusions.

Standards

The extruded polystyrene content of IKO enertherm Upstand Board is manufactured in accordance with BS EN 13164, EN 50001 Energy Management Systems, OHSAS 18001 Occupational Health and Safety Management Systems, ISO 14001 Environmental Management Systems, and ISO 9001 Quality Management Systems, as certified by Bureau Veritas.

Environmental

IKO enertherm XPS represents no known threat to the environment and has zero Ozone Depletion Potential (ODP) and a Global Warming Potential (GWP) of less than five. IKO enertherm XPS is non bio-degradable and 100% recyclable.



Benefits

- Integral weather resistant facing
- Excellent thermal performance
- Easy to install one-piece facing and insulation solution

Thermal performance

The extruded polystyrene content of IKO enertherm Upstand Board has a thermal conductivity of **0.033 W/mK**, the facing board has a thermal conductivity of 0.47W/mK.

Durability

The continuous service temperature limit of IKO enertherm Upstand Board is up to +70° C.

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Thickness (mm)	Thermal Conductivity (W/mK)	Thermal Conductivity (m ² K/W)	Length (mm)	Width (mm)	Compressive strength (kPa)
50/6	0.033 / 0.47	1.50 / 0.012	600	1200	200
100/6	0.033 / 0.47	3.00 / 0.012	600	1200	200
100/6	0.033 / 0.47	3.00 / 0.012	1200	2400	200

Fire Performance

The weather resistant facing board on IKO enertherm Upstand Board is has a reaction to fire classification of A1 in accordance with clause 8 of EN13501:1-2007.

Moisture absorption

IKO enertherm Upstand Board has a moisture absorption of 0.6% by volume when tested in accordance with EN 12087.

Vapour resistance

The XPS content of IKO enertherm Upstand Board has a water vapour resistivity of 625MNs/g.m when tested in accordance with EN 12086.

Decoration

The external grade board can be decorated if required. The board does not require priming and can be painted with alkali resistant paints such as acrylics, chlorinated rubber, epoxy, PVA, PVC, polyurethane and silicate.

Handling and storage

IKO enertherm Upstand Board is lightweight and easy to handle and install; the boards should be cut to size using a tungsten carbide tipped (TCT) saw, when cutting through the facing material it is advisable to wear a facemask. IKO enertherm Upstand Board is supplied on pallets, labelled with identifying product and manufacturing data and wrapped in a polythene shroud for temporary protection during transit and on site. Ensure the boards are not stored close to open flames or other ignition sources, also avoid volatile compounds and chemicals such as solvents. IKO enertherm XPS products should not be left exposed to prolonged sunlight as this will result in surface degradation. Where outside storage for extended periods is required, cover with opaque/light coloured sheeting. The facing board on IKO enertherm Upstand Board should have edges and corners protected to prevent chipping.

Installation

IKO enertherm Upstand Boards should be loose laid over the roof waterproofing system and held in position at the base of the upstand by the inverted roof build up installed to the main field area of the roof I.E. The enertherm XPS insulation and surface finishes. The top of the upstand board should be secured by a retention clip or suitable flashing arrangement

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